

On page 31, line 3, please change "gas feed 310" to --top gas feed 312--.

On page 31, line 5, please change "308 passage" to --passage 308--.

On page 31, line 6, please change "gas channel 304" to --gas channel 344--.

Q6 On page 31, line 12, please change "A first" to -Referring back to Figure 13, a first--

On page 31, line 18, please change "The gas introduced" to --The gases introduced--.

B7 On page 31, line 19, please change "nozzle 64 and O₂ are" to -nozzle, such as SiH₄ and O₂, are--.

On page 33, line 11, please change "gas 522 connection" to --gas connection 522--.

On page 33, line 12, after "connects" please delete "to".

IN THE CLAIMS:

Please cancel claims 1- 14 without prejudice and amend the claims as follows:

1. (Cancel) An apparatus for processing substrates, comprising:
 - (a) a chamber having:
 - (i) a sidewall;
 - (ii) a lid disposed at one end of the sidewall; and
 - (iii) a bottom disposed at the opposite end of the sidewall;
 - (b) a substrate support member cantilever mounted on the sidewall;
 - (c) one or more gas inlets disposed through one or more of the sidewall and the lid to admit gas into the chamber;
 - (d) one or more gas inlets disposed through one or more of the sidewall and the lid to admit one or more cleaning gases into the chamber; and
 - (e) an exhaust port disposed in the bottom of the chamber.
2. (Cancel) The apparatus of claim 1 wherein the lid comprises a dome comprised of a dielectric material.
3. (Cancel) The apparatus of claim 2 wherein the dome comprises a material selected from the group consisting of Al₂O₃, AlN, SiO₂ or combinations thereof.

4. (Cancel) The apparatus of claim 3 wherein the dome further comprises a generally annular sidewall and a generally planar top.
5. (Cancel) The apparatus of claim 2 further comprising a heat transfer assembly disposed adjacent to the lid.
6. (Cancel) The apparatus of claim 5 wherein the heat transfer assembly comprises one or more heat transfer plates.
7. (Cancel) The apparatus of claim 6 wherein the one or more heat transfer plates comprise a heating plate and a cooling plate.
8. (Cancel) The apparatus of claim 7 wherein the heating and cooling plates are comprised of a thermally conductive material.
9. (Cancel) The apparatus of claim 8 wherein the thermally conductive material is selected from the group consisting of AlN, SiN, Al or combinations thereof.
10. (Cancel) The apparatus of claim 9 wherein the heating plate includes a resistive heating element disposed therein.
11. (Cancel) The apparatus of claim 10 wherein the cooling plate includes one or more fluid passages disposed therein.
12. (Cancel) The apparatus of claim 11 wherein a heat conducting member is disposed between the heating plate and the cooling plate.

13. (Cancel) The apparatus of claim 12 wherein the heat conducting member comprises a heat transfer material such as grafoil, chromerics, or combinations thereof.

14. (Cancel) The apparatus of claim 13 wherein the heat conducting member comprises one or more pucks disposed between the heating and cooling plates.

Please add new claims 15 – 32 as follows:

15. (New) An electrically symmetric processing enclosure, comprising:

a chamber body defining an annular interior processing region, the annular processing region tapering towards a lower end;

an exhaust passage concentrically positioned in the lower end of the chamber body;

a cantilever mounted annular substrate support member affixed to the chamber body at a position above and concentric to the exhaust passage; and

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a lid member disposed over an annular open top portion of the chamber body, the lid member having an energy transmitting dome, energy delivery assembly, and a temperature control assembly mounted thereto.

16. (New) The processing enclosure of claim 15, wherein the cantilevered mounted substrate support member comprises:

a base member having a flange extending therefrom, the flange being configured to attach to an interior surface of the chamber body and form a smooth surface therewith;

at least one cantilevered arm portion extending radially inward from the base member; and

a substrate receiving member mounted to a distal end of the at least one cantilevered arm portion, the substrate receiving member having an annular outer surface.

17. (New) The processing enclosure of claim 16, wherein the annular outer surface defines an annular passage between the outer surface and the annular interior processing region.

18. (New) The processing enclosure of claim 16, wherein the at least one cantilevered arm portion includes a substantially hollow interior portion configured to transmit fluids therethrough.

19. (New) The processing enclosure of claim 15, wherein the energy transmitting dome comprises an cylindrical sidewall that is closed at a first end by a flat top, wherein the cylindrical sidewall is generally perpendicular to an upper surface of the substrate receiving member and the flat top is generally parallel to the upper surface.

20. (New) The processing enclosure of claim 19, wherein a junction between the cylindrical sidewall and the flat top is rounded to provide a curvilinear inner wall of the energy transmitting dome.

21. (New) The processing enclosure of claim 17, wherein the exhaust passage is concentrically positioned below the annular passage between the outer surface and the annular interior processing region and provides even gas flow through the annular passage.

22. (New) The processing enclosure of claim 15, wherein the chamber body includes at least one entry port formed therein, the cantilever mounted substrate support member accessing the annular interior processing region via the at least one entry port.

23. (New) An apparatus for processing substrates, comprising:
a chamber body having an annular inner sidewall portion and a bottom portion;

a pumping aperture positioned in a central location in the bottom portion, the pumping aperture being in fluid communication with a vacuum pump;

an annular substrate support member cantilever mounted to the sidewall portion, an outer perimeter of the annular substrate support member having a radius that is smaller than a radius of the annular sidewall portion; and

a lid member configured to close an open top portion of the chamber body, the lid member including a dome shaped upper portion configured to transmit energy therethrough.

24. (New) The apparatus of claim 23, wherein the lid member further comprises an energy delivery assembly and a temperature control assembly mounted thereto.

25. (New) The apparatus of claim 23, wherein the outer perimeter of the annular substrate support member and the annular inner sidewall cooperatively form an annularly shaped aperture therebetween.

26. (New) The apparatus of claim 23, wherein the pumping aperture is concentrically positioned below the annular substrate support member.

27. (New) The apparatus of claim 23, wherein the substrate support member comprises:

a base member having a flange extending therefrom, the flange being configured to attach to an interior surface of the chamber body and form a smooth surface therewith;

at least one cantilevered arm extending radially inward toward a central location in the chamber body from the base member; and

a disk shaped substrate receiving member affixed to a distal end of the at least one cantilevered arm portion, the substrate receiving member having an annular perimeter and a substantially planar upper substrate support surface.

28. (New) The apparatus of claim 23, wherein the dome shaped upper portion comprises a cylindrical sidewall connecting to a top portion at a first end, wherein the cylindrical sidewall is perpendicular to an upper surface of the substrate support member.

29. (New) The apparatus of claim 23, wherein the energy delivery system comprises at least one coil positioned proximate the dome shaped upper portion.

30. (New) The apparatus of claim 23, wherein the chamber body includes a first entry port formed therein, the first entry port being configured to receive the cantilever mounted substrate support member therethrough.

32. (New) The apparatus of claim 30, wherein the cantilever mounted substrate support member attaches to the chamber body in a manner that maintains a smooth arc shape on the annular inner sidewall.